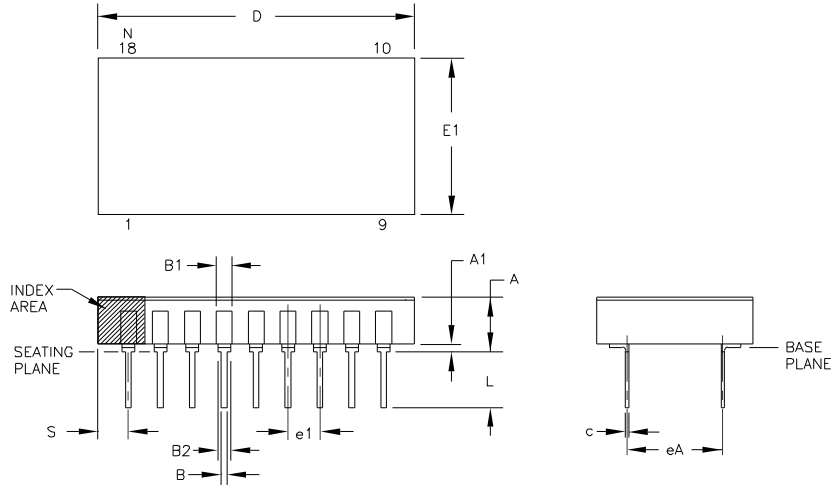


Package Number 220 - 18-Lead Bottom Braze DIP, .300 Wide



DIM	INCHES		MILLIMETERS		NOTE
	MIN.	MAX.	MIN.	MAX.	
A	.148	.197	3.76	5.00	
A1	.015	.035	0.38	0.89	
B	.016	.020	0.41	0.51	
B1	.050 TYP.		1.27 TYP.		
B2	.040 TYP.		1.02 TYP.		
c	.009	.012	0.23	0.30	
D	.982	1.002	24.94	25.45	
E1	.480	.500	12.19	12.70	
e1	.095	.105	2.41	2.67	
eA	.290	.310	7.37	7.87	
L	.150	.200	3.81	5.08	
N	18		18		
S	.038	.103	0.97	2.62	

NOTES:

- LEADS IN TRUE POSITION WITHIN .010" (0.25mm) R @ MMC AT SEATING PLANE.
- PIN NUMBERS SHOWN FOR REFERENCE ONLY. NUMBERS MAY NOT BE MARKED ON PACKAGE.
- A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ220 REV.: C
 JEDEC NUMBER: NONE



PACKAGE DRAWING

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